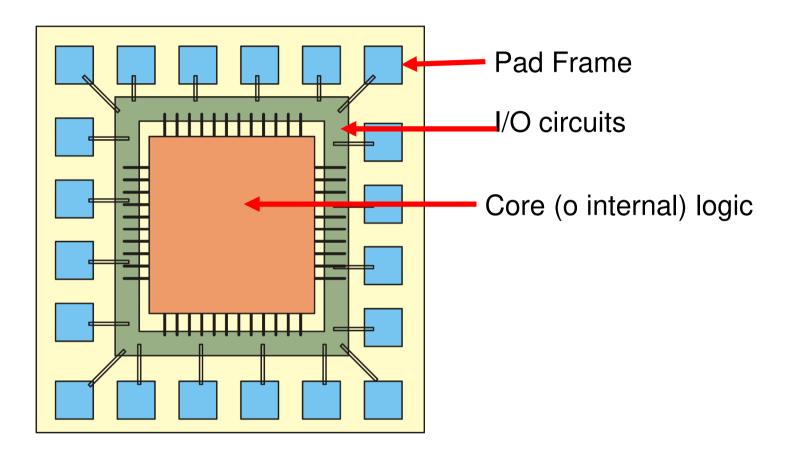
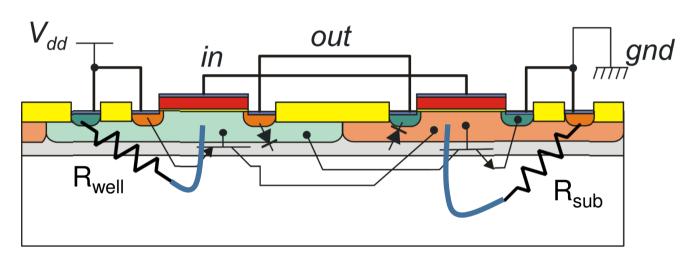
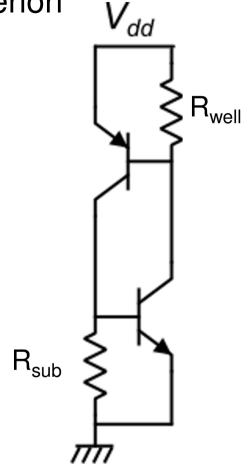
Typical structure of a digital chip



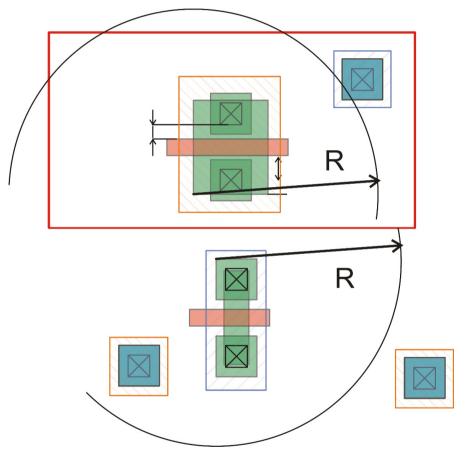
Recall to the letch-up phenomenon



In order to reduce the risk of latch-up, it is important to reduce the resistances between the parasitic BJT bases and the substrate and well tap



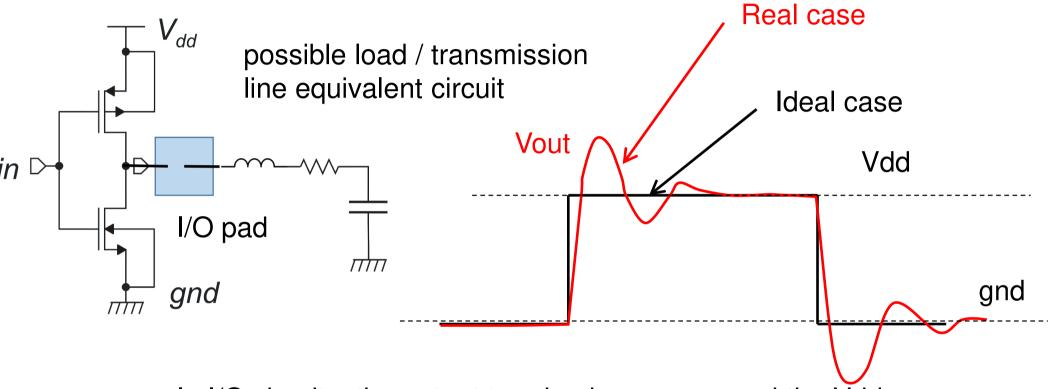
Latch-up layout rules: core logic



Every part of a p-active area in an n-well must "see" at least one well-tap with a maximum distance R

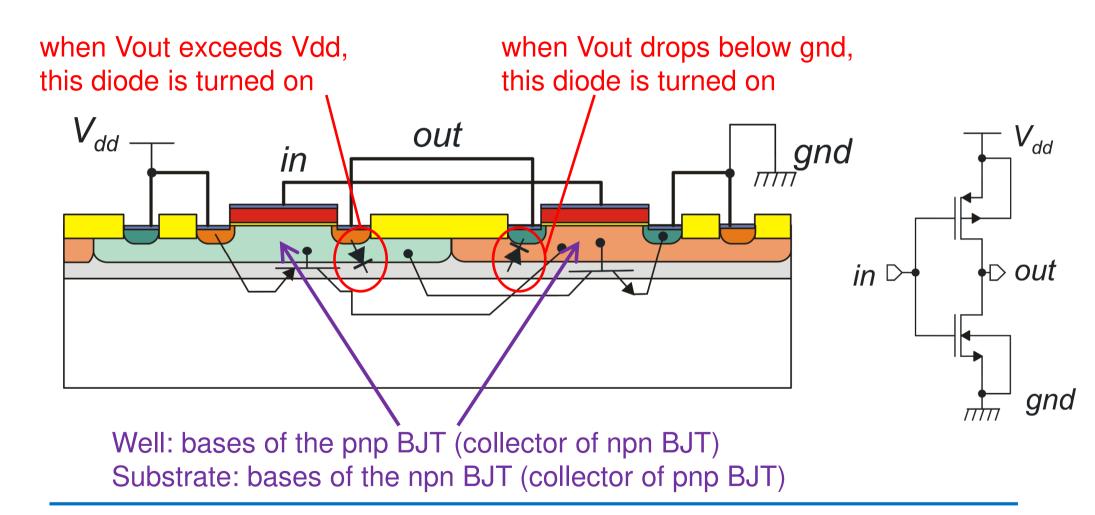
Every part of an n-active area in the substrate (p-well) must "see" at least one substrate-tap with a maximum distance R

I/O circuits: over-voltage risk



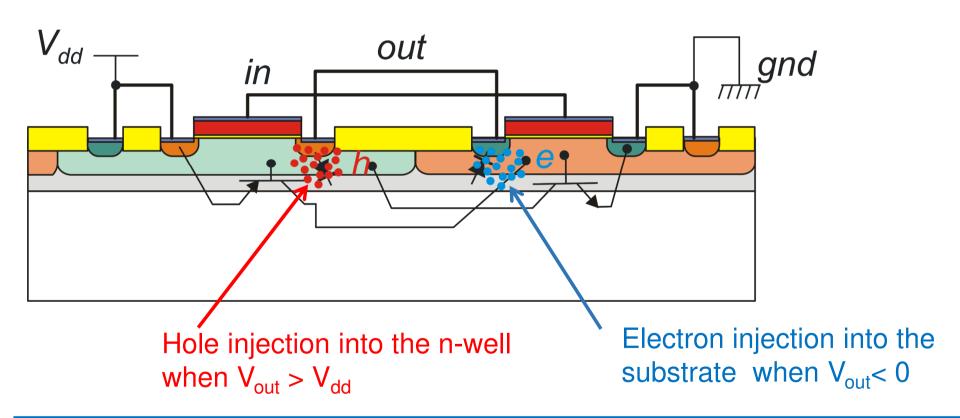
In I/O circuits, the output termination can exceed the Vdd or gnd rails. This introduces additional risk of latch-up

Injection of minority carriers



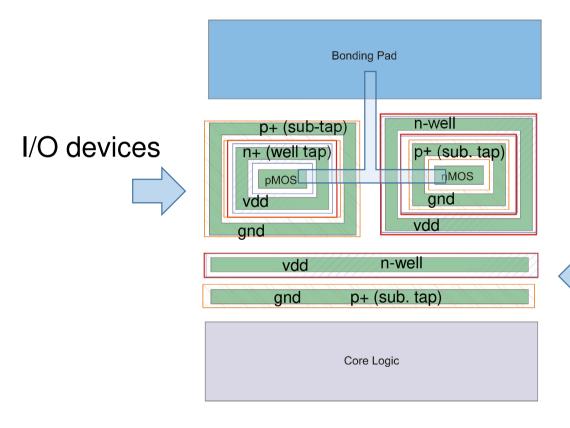
Injection of minority carriers

Injection of minority charge carriers into the parasitic BJTs bases may trigger the latch-up phenomenon



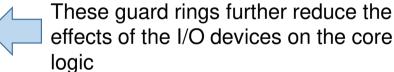
I/O devices: Guard Rings

I/O circuits require additional protection against latch-up



Guard rings are placed around the I/O devices in order to:

- Reduce the resistance between drain/body diffusions to gnd (nMOS) or Vdd (pMOS)
- Collect most of the minority carriers injected by one device before they reach neighboring devices



Analog and mixed signal chips

- For the analog section of a System on a Chip, it is not convenient or even impossible to divide the circuit into a core section and an I/O section.
- However, the same rules illustrated for digital chips apply to the output devices of the analog cells (for example, operational amplifiers), which are connected to output pads. High density of substrate / well contacts, guard-rings and particular layout configurations are common practice for the output devices of analog circuits.